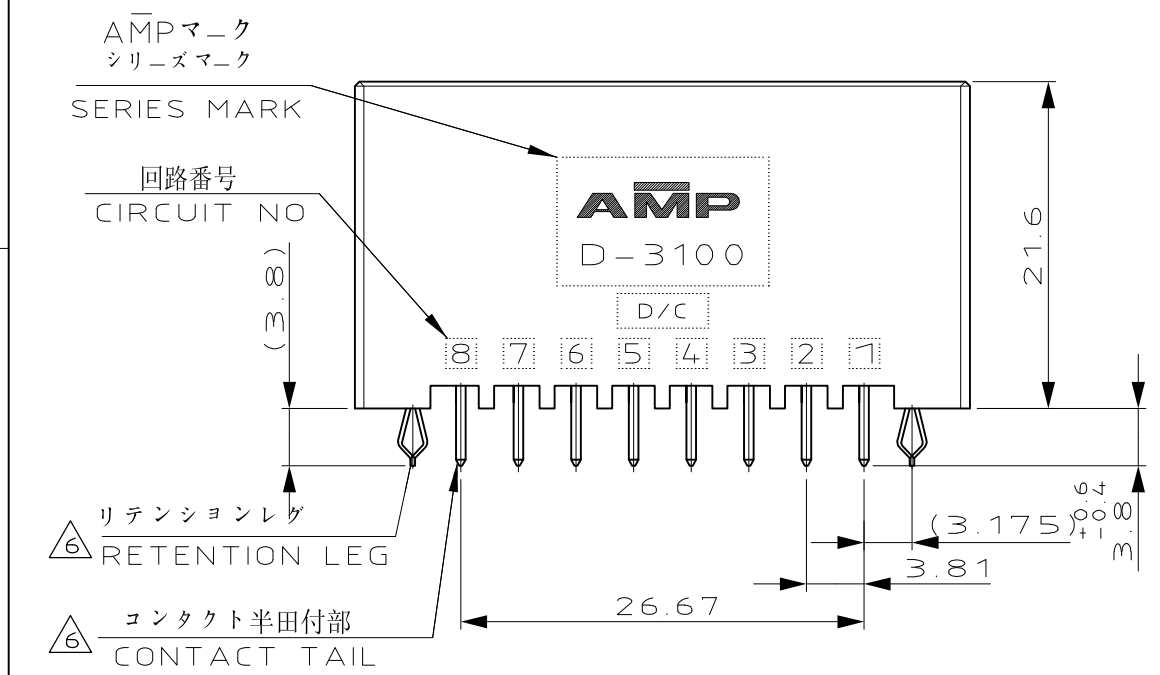
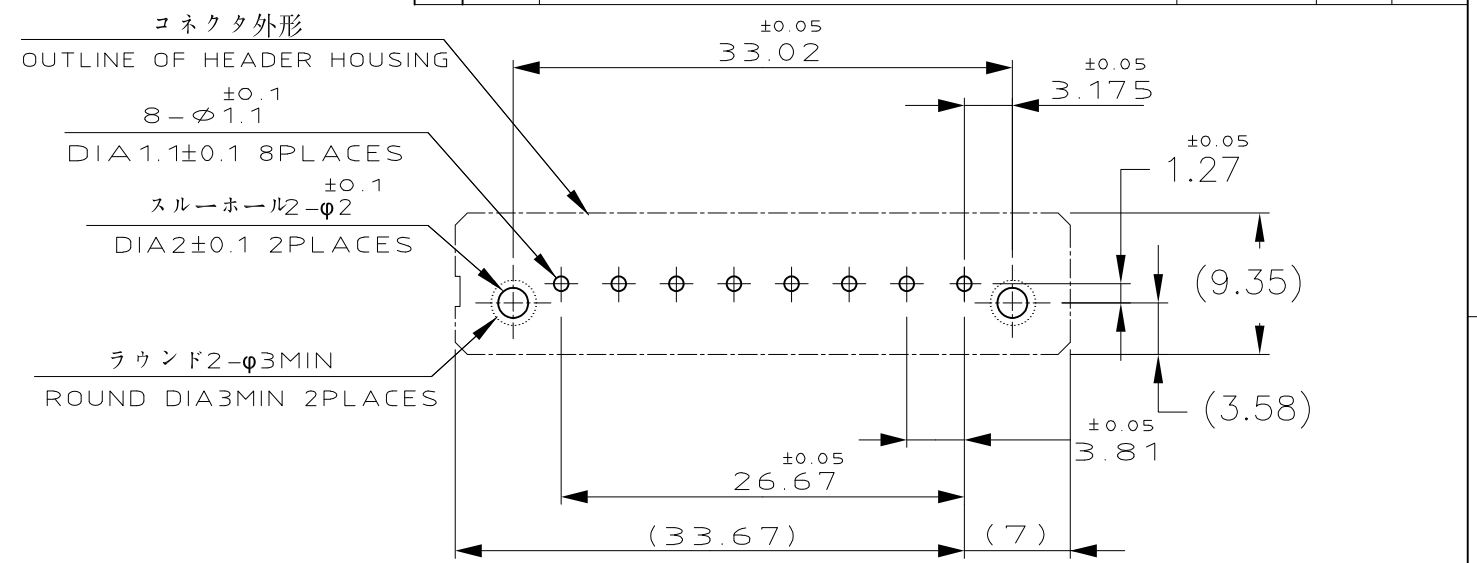
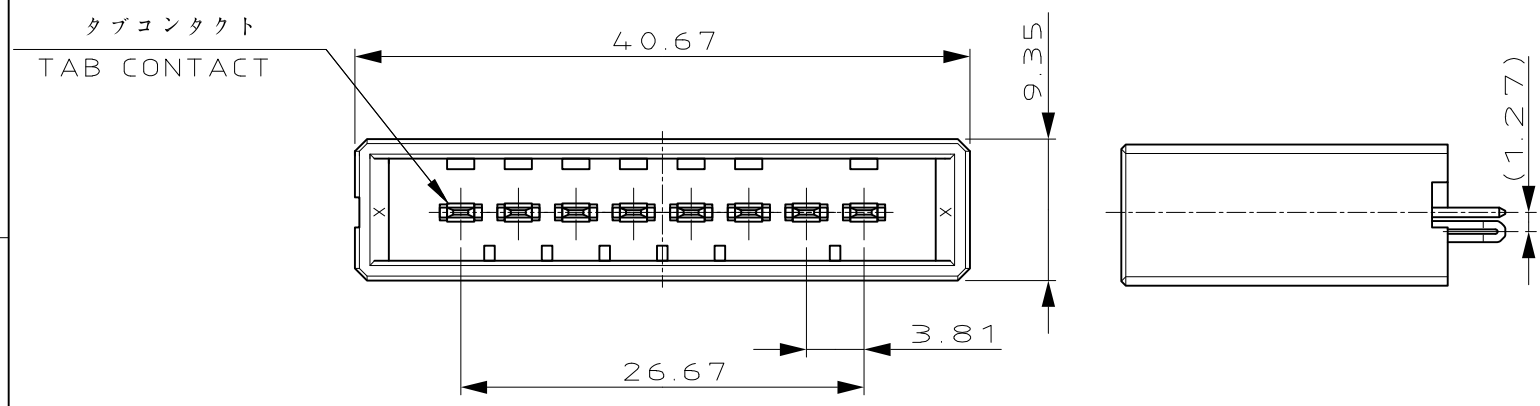


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LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
J	-	F	REVISED	04JUL2012	H.M N.Y



推奨基板取付け穴寸法
 PC 基板厚: 1.6 ± 0.1
 (非累積公差)
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6 ± 0.1
 (NOT ACCUMULATE TOLERANCE)
 (CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK
 CONTACT: COPPER ALLOY
 RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒
 コンタクト: 銅合金
 リテンションレグ: 銅合金
- めっき: コンタクト全面 Ni 下地
 接触部 0.38 μm MIN 金めっき
- めっき: コンタクト全面 Ni 下地
 接触部 0.76 μm MIN 金めっき
- めっき: コンタクト全面 Ni 下地
 接触部 2.0 μm MIN スズめっき
- めっき: リテンションレグとコンタクト半田付部
 ニッケル下地の土に半田めっき
- めっき: リテンションレグとコンタクト半田付部
 ニッケル下地の土にスズめっき

△6	△4	1-178317-5
△6	△3	1-178317-3
△6	△2	1-178317-2
(FINISH)		製品番号 (PART NO.)

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	19APR1994		TE Connectivity
		CHK	20APR1994		
		APVD	20APR1994		
		PRODUCT SPEC			
DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:	NAME		8 POS SINGLE ROW	
mm	0 PLC ±	S.MANABE		VERTICAL HDR ASSY FOR DYNAMIC D-3100	
	1 PLC ±	S.MANABE			
	2 PLC ±10° ±0.3	APPLICATION SPEC			
	3 PLC ±10° 30° ±0.4	SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
	4 PLC ±30° 100° ±0.45	A300779		C-178317	
	ANGLES ±3°	SCALE	2:1		SHEET
MATERIAL	FINISH	CUSTOMER DRAWING		1 OF 1	REV
SEE NOTE	SEE NOTE				F

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)